

# **CD74HC154, CD74HCT154**

**High Speed CMOS Logic  
4-to-16 Line Decoder/Demultiplexer**

## **Features**

- Two Enable Inputs to Facilitate Demultiplexing and Cascading Functions
- Fanout (Over Temperature Range)
  - Standard Outputs ..... 10 LSTTL Loads
  - Bus Driver Outputs ..... 15 LSTTL Loads
- Wide Operating Temperature Range ... -55°C to 125°C
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- HC Types
  - 2V to 6V Operation
  - High Noise Immunity:  $N_{IL} = 30\%$ ,  $N_{IH} = 30\%$  of  $V_{CC}$  at  $V_{CC} = 5V$
- HCT Types
  - 4.5V to 5.5V Operation
  - Direct LSTTL Input Logic Compatibility,  $V_{IL} = 0.8V$  (Max),  $V_{IH} = 2V$  (Min)
  - CMOS Input Compatibility,  $I_l \leq 1\mu A$  at  $V_{OL}, V_{OH}$

## **Description**

The Harris CD74HC154 and CD74HCT154 are 4-to-16 line decoders/demultiplexers with two enable inputs, E1 and E2. A High on either enable input forces the output into the High state. The demultiplexing function is performed by using the four input lines, A0 to A3, to select the output lines  $\bar{Y}_0$  to  $\bar{Y}_{15}$ , and using one enable as the data input while holding the other enable low.

## **Ordering Information**

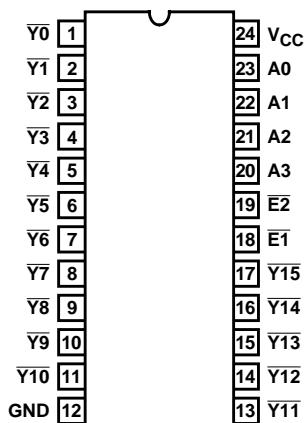
PART NUMBER	TEMP. RANGE (°C)	PACKAGE	PKG. NO.
CD74HC154E	-55 to 125	24 Ld PDIP	E24.6
CD74HCT154E	-55 to 125	24 Ld PDIP	E24.6
CD74HC154EN	-55 to 125	24 Ld PDIP	E24.3
CD74HC154EN	-55 to 125	24 Ld PDIP	E24.3
CD74HC154M	-55 to 125	24 Ld SOIC	M24.3
CD74HCT154M	-55 to 125	24 Ld SOIC	M24.3

### NOTES:

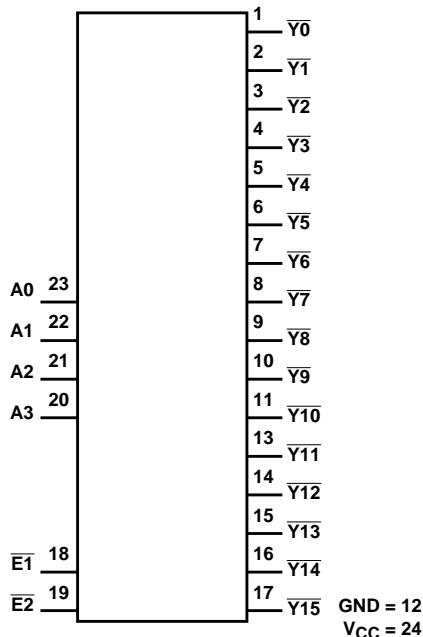
1. When ordering, use the entire part number. Add the suffix 96 to obtain the variant in the tape and reel.
2. Wafer or die for this part number is available which meets all electrical specifications. Please contact your local sales office or Harris customer service for ordering information.

## **Pinout**

**CD74HC154, CD74HCT154  
(PDIP, SOIC)  
TOP VIEW**



**Functional Diagram**



**TRUTH TABLE**

INPUTS						OUTPUTS															
E1	E2	A3	A2	A1	A0	Y0	Y1	Y2	Y3	Y4	Y5	Y6	Y7	Y8	Y9	Y10	Y11	Y12	Y13	Y14	Y15
L	L	L	L	L	L	H	H	H	H	H	H	H	H	H	H	H	H	H	H	H	
L	L	L	L	L	H	H	L	H	H	H	H	H	H	H	H	H	H	H	H	H	
L	L	L	L	H	L	H	H	L	H	H	H	H	H	H	H	H	H	H	H	H	
L	L	L	L	H	H	H	H	L	H	H	H	H	H	H	H	H	H	H	H	H	
L	L	L	H	L	L	H	H	H	H	L	H	H	H	H	H	H	H	H	H	H	
L	L	L	H	L	H	H	H	H	H	H	L	H	H	H	H	H	H	H	H	H	
L	L	L	H	H	L	H	H	H	H	H	H	L	H	H	H	H	H	H	H	H	
L	L	L	H	H	H	H	H	H	H	H	H	H	H	L	H	H	H	H	H	H	
L	L	H	L	L	L	H	H	H	H	H	H	H	H	H	L	H	H	H	H	H	
L	L	L	H	L	H	H	H	H	H	H	H	H	H	H	L	H	H	H	H	H	
L	L	H	L	H	L	H	H	H	H	H	H	H	H	H	L	H	H	H	H	H	
L	L	H	L	H	L	H	H	H	H	H	H	H	H	H	H	L	H	H	H	H	
L	L	H	H	L	L	H	H	H	H	H	H	H	H	H	H	H	L	H	H	H	
L	L	H	H	H	L	H	H	H	H	H	H	H	H	H	H	H	L	H	H	H	
L	L	H	H	H	H	H	H	H	H	H	H	H	H	H	H	H	H	H	H	H	
L	H	X	X	X	X	H	H	H	H	H	H	H	H	H	H	H	H	H	H	H	
H	L	X	X	X	X	H	H	H	H	H	H	H	H	H	H	H	H	H	H	H	
H	H	X	X	X	X	H	H	H	H	H	H	H	H	H	H	H	H	H	H	H	

NOTE: H = High Voltage Level, L = Low Voltage Level, X = Don't Care

**Absolute Maximum Ratings**

DC Supply Voltage, V <sub>CC</sub> .....	-0.5V to 7V
DC Input Diode Current, I <sub>IK</sub>	
For V <sub>I</sub> < -0.5V or V <sub>I</sub> > V <sub>CC</sub> + 0.5V .....	±20mA
DC Output Diode Current, I <sub>OK</sub>	
For V <sub>O</sub> < -0.5V or V <sub>O</sub> > V <sub>CC</sub> + 0.5V .....	±20mA
DC Output Source or Sink Current per Output Pin, I <sub>O</sub>	
For V <sub>O</sub> > -0.5V or V <sub>O</sub> < V <sub>CC</sub> + 0.5V .....	±25mA
DC V <sub>CC</sub> or Ground Current, I <sub>CC</sub> or I <sub>GND</sub> .....	±50mA

**Thermal Information**

Thermal Resistance (Typical, Note 3)	θ <sub>JA</sub> (°C/W)
PDIP Package (.300) .....	75
PDIP Package (.600) .....	60
SOIC Package .....	75
Maximum Junction Temperature .....	150°C
Maximum Storage Temperature Range .....	-65°C to 150°C
Maximum Lead Temperature (Soldering 10s) .....	300°C
(SOIC - Lead Tips Only)	

**Operating Conditions**

Temperature Range (T <sub>A</sub> ) .....	-55°C to 125°C
Supply Voltage Range, V <sub>CC</sub>	
HC Types .....	.2V to 6V
HCT Types .....	.45V to 5.5V
DC Input or Output Voltage, V <sub>I</sub> , V <sub>O</sub> .....	0V to V <sub>CC</sub>
Input Rise and Fall Time	
2V .....	1000ns (Max)
4.5V .....	500ns (Max)
6V .....	400ns (Max)

*CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.*

## NOTE:

3. θ<sub>JA</sub> is measured with the component mounted on an evaluation PC board in free air.

**DC Electrical Specifications**

PARAMETER	SYMBOL	TEST CONDITIONS		V <sub>CC</sub> (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
		V <sub>I</sub> (V)	I <sub>O</sub> (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
<b>HC TYPES</b>												
High Level Input Voltage	V <sub>IH</sub>	-	-	2	1.5	-	-	1.5	-	1.5	-	V
				4.5	3.15	-	-	3.15	-	3.15	-	V
				6	4.2	-	-	4.2	-	4.2	-	V
Low Level Input Voltage	V <sub>IL</sub>	-	-	2	-	-	0.5	-	0.5	-	0.5	V
				4.5	-	-	1.35	-	1.35	-	1.35	V
				6	-	-	1.8	-	1.8	-	1.8	V
High Level Output Voltage CMOS Loads	V <sub>OH</sub>	V <sub>IH</sub> or V <sub>IL</sub>	-0.02	2	1.9	-	-	1.9	-	1.9	-	V
			-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
			-0.02	6	5.9	-	-	5.9	-	5.9	-	V
High Level Output Voltage TTL Loads			-	-	-	-	-	-	-	-	-	V
			-4	4.5	3.98	-	-	3.84	-	3.7	-	V
			-5.2	6	5.48	-	-	5.34	-	5.2	-	V
Low Level Output Voltage CMOS Loads	V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub>	0.02	2	-	-	0.1	-	0.1	-	0.1	V
			0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
			0.02	6	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads			-	-	-	-	-	-	-	-	-	V
			4	4.5	-	-	0.26	-	0.33	-	0.4	V
			5.2	6	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	I <sub>I</sub>	V <sub>CC</sub> or GND	-	6	-	-	±0.1	-	±1	-	±1	µA
Quiescent Device Current	I <sub>CC</sub>	V <sub>CC</sub> or GND	0	6	-	-	8	-	80	-	160	µA

# CD74HC154, CD74HCT154

## DC Electrical Specifications (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS		V <sub>CC</sub> (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
		V <sub>I</sub> (V)	I <sub>O</sub> (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
<b>HCT TYPES</b>												
High Level Input Voltage	V <sub>IH</sub>	-	-	4.5 to 5.5	2	-	-	2	-	2	-	V
Low Level Input Voltage	V <sub>IL</sub>	-	-	4.5 to 5.5	-	-	0.8	-	0.8	-	0.8	V
High Level Output Voltage CMOS Loads	V <sub>OH</sub>	V <sub>IH</sub> or V <sub>IL</sub>	-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
High Level Output Voltage TTL Loads			-4	4.5	3.98	-	-	3.84	-	3.7	-	V
Low Level Output Voltage CMOS Loads	V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub>	0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads			4	4.5	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	I <sub>I</sub>	V <sub>CC</sub> and GND	0	5.5	-		±0.1	-	±1	-	±1	µA
Quiescent Device Current	I <sub>CC</sub>	V <sub>CC</sub> or GND	0	5.5	-	-	8	-	80	-	160	µA
Additional Quiescent Device Current Per Input Pin: 1 Unit Load	ΔI <sub>CC</sub>	V <sub>CC</sub> -2.1	-	4.5 to 5.5	-	100	360	-	450	-	490	µA

NOTE: For dual-supply systems theoretical worst case (V<sub>I</sub> = 2.4V, V<sub>CC</sub> = 5.5V) specification is 1.8mA.

## HCT Input Loading Table

INPUT	UNIT LOADS
A0 - A3	1.4
E1, E2	1.3

NOTE: Unit Load is ΔI<sub>CC</sub> limit specified in DC Electrical Table, e.g., 360µA max at 25°C.

## Switching Specifications Input t<sub>r</sub>, t<sub>f</sub> = 6ns

PARAMETER	SYMBOL	TEST CONDITIONS	V <sub>CC</sub> (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
<b>HC TYPES</b>											
Propagation Delay (Figure 1) Address to Output	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	2	-	-	175	-	220	-	265	ns
			4.5	-	-	35	-	44	-	53	ns
		C <sub>L</sub> = 15pF	5	-	14	-	-	-	-	-	ns
		C <sub>L</sub> = 50pF	6	-	-	30	-	37	-	45	ns
E1 to Output	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	2	-	-	175	-	220	-	265	ns
			4.5	-	-	35	-	44	-	53	ns
		C <sub>L</sub> = 15pF	5	-	14	-	-	-	-	-	ns
		C <sub>L</sub> = 50pF	6	-	-	30	-	37	-	45	ns

**Switching Specifications** Input  $t_r, t_f = 6\text{ns}$  (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS	V <sub>CC</sub> (V)	25°C			-40°C TO 85°C		-55°C TO 125°C	
				MIN	TYP	MAX	MIN	MAX	MIN	MAX
E2 to Output	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	2	-	-	175	-	220	-	265
			4.5	-	-	35	-	44	-	53
		C <sub>L</sub> = 15pF	5	-	14	-	-	-	-	ns
		C <sub>L</sub> = 50pF	6	-	-	30	-	37	-	45
Output Transition Time (Figure 1)	t <sub>TLH</sub> , t <sub>THL</sub>	C <sub>L</sub> = 50pF	2	-	-	75	-	95	-	110
			4.5	-	-	15	-	19	-	22
			6	-	-	13	-	16	-	19
Input Capacitance	C <sub>IN</sub>	-	-	-	-	10	-	10	-	10
Power Dissipation Capacitance (Notes 4, 5)	C <sub>PD</sub>	-	5	-	88	-	-	-	-	pF
<b>HCT TYPES</b>										
Propagation Delay (Figure 2) Address to Output	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	4.5	-	-	35	-	44	-	53
			C <sub>L</sub> = 15pF	5	-	14	-	-	-	ns
E1 to Output	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	4.5	-	-	34	-	43	-	51
			C <sub>L</sub> = 15pF	5	-	14	-	-	-	ns
E2 to Output	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	4.5	-	-	34	-	43	-	51
			C <sub>L</sub> = 15pF	5	-	14	-	-	-	ns
Output Transition Time	t <sub>TLH</sub> , t <sub>THL</sub>	C <sub>L</sub> = 50pF	4.5	-	-	15	-	19	-	22
Input Capacitance	C <sub>IN</sub>	-	-	-	-	10	-	10	-	10
Power Dissipation Capacitance (Notes 4, 5)	C <sub>PD</sub>	-	5	-	84	-	-	-	-	pF

## NOTES:

4. C<sub>PD</sub> is used to determine the dynamic power consumption, per gate.  
 5. P<sub>D</sub> = V<sub>CC</sub><sup>2</sup> f<sub>i</sub> (C<sub>PD</sub> + C<sub>L</sub>) where f<sub>i</sub> = input frequency, C<sub>L</sub> = output load capacitance, V<sub>CC</sub> = supply voltage.

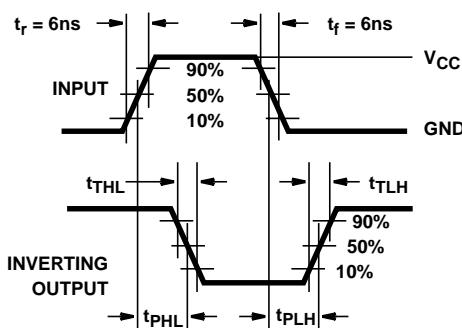
**Test Circuits and Waveforms**

FIGURE 1. HC AND HCU TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

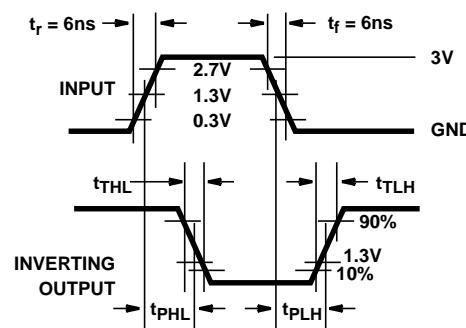


FIGURE 2. HCT TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

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